

## Application Data Sheet

### Application Information

Application Type:: Regular  
Subject Matter:: Utility  
Title:: Die Bonding Apparatus With Automatic  
Die And Lead Frame Image Matching System  
Attorney Docket Numer:: IDT-1661  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Suggested Drawing Figure:: 4  
Total Drawing Sheets:: 3  
Small Entity:: No  
Petition included?:: No  
Secrecy Order in Parent Appl.?:: No

### Inventor Information

Inventor Authority type:: Inventor  
Primary Citizenship Country:: Malaysia  
Status:: Full Capacity  
Given Name:: Kong  
Middle Name:: Lam  
Family Name:: Song  
City of Residence:: Penang  
Country of Residence:: Malaysia  
Street:: 21, Tingkat Bukit Kecil 2,  
Taman Sri Nibong, 11900, Bayan Lepas  
City:: Penang  
Country:: Malaysia

### Correspondence Information

Correspondence Customer Number:: 027158  
Phone number:: 408-451-5902  
Fax number:: 408-451-5908  
E-Mail address:: pbever@beverlaw.com

### Representative Information

Representative Customer Number:: 027158

**Foreign Priority Information**

|           |                      |               |
|-----------|----------------------|---------------|
| Country:: | Application Number:: | Filing Date:: |
| Malaysia  | PI 20012544          | 05/29/01      |

**Assignee Information**

Assignee Name:: Integrated Device Technology, Inc.